

Title (en)
ADDITIVE FOR MOLDING OF CERAMIC MATERIAL

Title (de)
ADDITIVE ZUM FORMEN EINES KERAMIKMATERIALS

Title (fr)
ADDITIF POUR LE MOULAGE DE MATÉRIAU CÉRAMIQUE

Publication
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Application
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Priority

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Abstract (en)
[origin: EP2615074A1] The present invention relates to an additive for use in the molding of a ceramic material, which exhibits satisfactory water absorption performance in a ceramic green ceramic clay, can highly achieve both high fluidability and low loading performance during extrusion molding and high shape-retaining performance after extrusion at the same time, and comprises polymer microparticles. This additive for use in the molding of a ceramic material comprises polymer microparticles, is characterized in that the polymer microparticles have an average particle size between 10 and 150 μm when the polymer microparticles are swollen with ion exchange water until the swollen polymer microparticles reach a saturated state and can absorb 10-60 mL/g of ion exchange water under ordinary pressure, and is also characterized in that an aqueous dispersion prepared by dispersing 1 part by mass of the polymer microparticles in 110 parts by mass of ion exchange water has an electrical conductivity of 1500 $\mu\text{S/cm}$ or less at 25°C.

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